

Pb RoHS

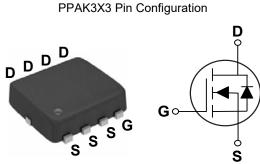
#### **General Description**

These N-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

BV <sub>DSS</sub>	R <sub>DS(ON)</sub>	Ι <sub>D</sub>
30V	10 mΩ	38 A

#### Features

- $R_{DS(ON)} \leq 10 m \Omega @V_{GS}$ =10V
- Improved dv/dt Capability
- Fast Switching
- Green Device Available



#### **Applications**

- DC DC Converters
- Portable Equipment Application

## Absolute Maximum Ratings T<sub>J</sub>=25°C unless otherwise noted

Symbol	Parameter	Rating	Units
V <sub>DS</sub>	Drain-Source Voltage	30	V
V <sub>GS</sub>	Gate-Source Voltage	±20	V
1	Drain Current - Continuous (T <sub>C</sub> =25°C)	38	Α
Ι <sub>D</sub>	Drain Current - Continuous (T <sub>C</sub> =100°C)	24	Α
I <sub>DM</sub>	Drain Current - Pulsed (T <sub>C</sub> =25°C) (NOTE 1)	52	А
EAS	Single Pulse Avalanche Energy (L=0.1mH) (NOTE 2)	16	mJ
IAS	Single Pulse Avalanche Current (L=0.1mH) (NOTE 2)	18	Α
PD	Power Dissipation (T <sub>C</sub> =25°C)	23	W
$T_J$	Operating Junction Temperature	150	°C
T <sub>STG</sub>	Storage Temperature Range	-50 to 150	°C
Marking Code		NC010	

Thermal Characteristics					
Symbol	Parameter	Rating	Unit		
$R_{ extsf{ heta}JA}$	Thermal Resistance Junction to Ambient	65	°C/W		
$R_{ extsf{ heta}JC}$	Thermal Resistance Junction to Case	5.4	°C/W		





## Electrical Characteristics (T<sub>J</sub>=25°C, unless otherwise noted)

Off Characteristics						
Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
$BV_{DSS}$	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V , I <sub>D</sub> =250uA	30			V
I <sub>DSS</sub>	Drain-Source Leakage Current	V <sub>DS</sub> =24V , V <sub>GS</sub> =0V			1	uA
I <sub>GSS</sub>	Gate-Source Leakage Current	V <sub>GS</sub> =±20V , V <sub>DS</sub> =0V			±100	nA

## **On Characteristics**

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
R <sub>DS(ON)</sub>	IStatic Drain-Source On-Resistance	V <sub>GS</sub> =10V , I <sub>D</sub> =10A			10	mΩ
		V <sub>GS</sub> =4.5V , I <sub>D</sub> =5A			13.8	
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>GS</sub> =V <sub>DS</sub> , I <sub>D</sub> =250uA	1.1		2.1	V
gfs	Forward Transconductance	V <sub>DS</sub> =5V , I <sub>DS</sub> =5A		2.6		S

## Dynamic and switching Characteristics (NOTE 4)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
$Q_g$	Total Gate Charge			20.4		
$Q_gs$	Gate-Source Charge	$V_{DS}$ =15V , $V_{GS}$ =10V , $I_{D}$ =10A		2.5		nC
$Q_gd$	Gate-Drain Charge			4.8		
T <sub>d(on)</sub>	Turn-On Delay Time	V <sub>DS</sub> =15V , V <sub>GS</sub> =10V , R <sub>GEN</sub> =3Ω , I <sub>D</sub> =1A		15.2		
Tr	Rise Time			28		nS
T <sub>d(off)</sub>	Turn-Off Delay Time			28.3		113
T <sub>f</sub>	Fall Time			14.1		
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> =15V , V <sub>GS</sub> =0V , F=1MHz		875		
C <sub>oss</sub>	Output Capacitance			112		pF
C <sub>rss</sub>	Reverse Transfer Capacitance			100		
R <sub>g</sub>	Gate Resistance	$V_{GS}$ =0V , $V_{DS}$ =0V , F=1MHz		3.4		Ω

## **Drain-Source Diode Characteristics and Ratings**

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
$V_{SD}$	Diode Forward Voltage	V <sub>GS</sub> =0V , I <sub>S</sub> =1A			1.1	V
t <sub>rr</sub>	Reverse Recovery Time	I <sub>F</sub> =1A , V <sub>R</sub> =20V ,		25.2		nS
Q <sub>rr</sub>	Reverse Recovery Charge	dI <sub>F</sub> /dt=100A/us		10.4		nC

NOTES :

1.Max. current is limited by bonding wire.

2.UIS tested and pulse width are limited by maximum junction temperature 150°C.

3.The data tested by pulsed , pulse width  $\leq$  300us , duty cycle  $\leq$  2%.

4. Guaranteed by design, not subject to production testing.



30V N-Channel MOSFETs

#### **Characteristics Curves**

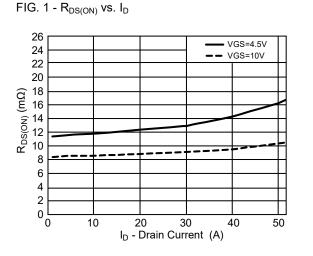


FIG. 3 - Source-Drain Diode Forward

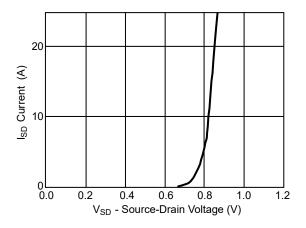


FIG. 2 - Gate Threshold Voltage

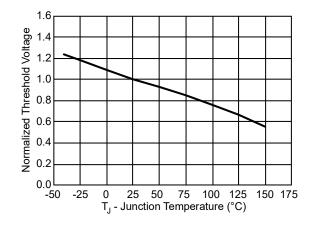


FIG. 4 - Gate Charge Characteristics

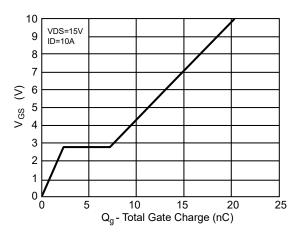


FIG. 5 - Safe Operating Area

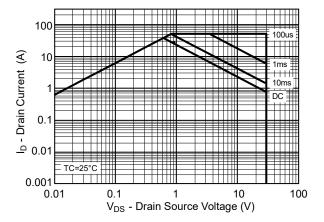
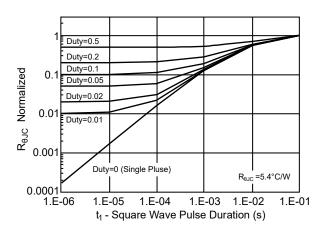


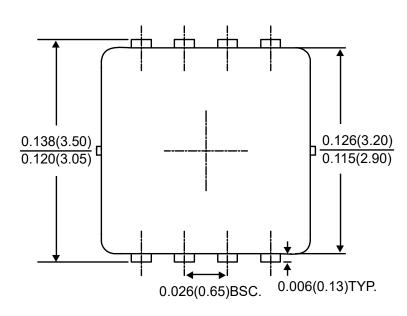
FIG. 6 -  $R_{\theta JC}$  Transient Thermal Impedance

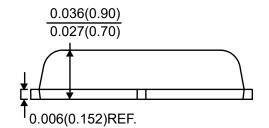


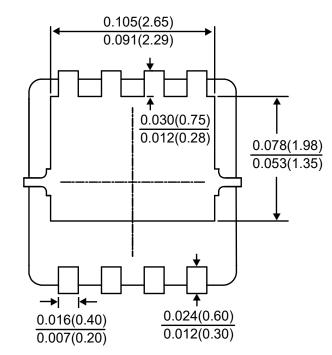


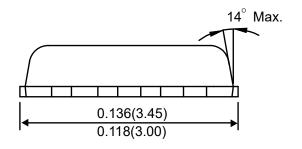


#### **Package Outline Dimensions**









## PPAK3X3

Dimensions in inches and (millimeters)



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